

REMARKS/ARGUMENTS

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1-6 are pending, with Claims 1, 3, and 5 amended by the present amendment.

In the Official Action, Claims 1-6 were rejected under 35 U.S.C. § 103(a) as being obvious over Hiraoka et al. (U.S. Patent No. 6,465,742, hereinafter H1) in view of Hiraoka et al. (U.S. Patent Publication 2003/0022102, hereinafter H2).

Claims 1, 3, and 5 are amended to describe Applicants' invention in varying language. Support for this amendment is found in Applicants' originally filed specification.¹ No new matter is added.

Briefly recapitulating, amended Claim 1 is directed to

An electronic device connecting method comprising:

mounting an electrode of an electronic device closely on a sheet-like porous member having pores, the porous member having a photosensitive layer formed on an inner surface of pores, the photosensitive layer producing or eliminating an ion exchange group by irradiation with energy beams on the inner surface of the pores;

selectively irradiating a predetermined region of the porous member, on which the electronic device is mounted, with energy beams thereby exposing the photosensitive layer to form a latent image in an irradiated or non-irradiated portion of the porous member, the predetermined region including a portion close to the electrode;

after said selectively irradiating, filling pores in the latent image of the porous member with a conductive material to simultaneously form a wiring portion and a via contact connected to the electrode; and

bonding the porous member, in which the wiring portion and the via contact is formed by said filling, to the electronic device.

¹ Specification, page 10, lines 13-19.

H1 describes a method of manufacturing a three-dimensional structure having a three-dimensional refractive index. H2 describes a method of manufacturing a composite member having a conductive pattern of form on a base material of an insulating body. However, both H1 and H2 do not disclose or suggest Applicants' step of "after said selective irradiating, filling pores in the latent image of the porous member with a conductive material to simultaneously form a wiring portion in a via contact connected to the electrode."

As none of the cited prior art, individually or in combination, discloses or suggests all the elements of independent Claim 1, Applicants submit the invention defined by Claim 1, and all claims depending therefrom, is not rendered obvious by the asserted references for at least the reasons stated above.²

Accordingly, in view of the present amendment and in light of the previous discussion, Applicants respectfully submit that the present application is in condition for allowance and respectfully request an early and favorable action to that effect.

Respectfully submitted,

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² MPEP § 2142 "...the prior art reference (or references when combined) must teach or suggest **all** the claim limitations.